RELIABILITY REPORT

FOR

MAX14690_EWX+T

WAFER LEVEL DEVICES

June 11, 2015

MAXIM INTEGRATED

160 RIO ROBLES

SAN JOSE, CA 95134

Approved by
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Quality Assurance
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Conclusion

The MAX14690_EWX+T successfully met the quality and reliability standards required of all Maxim Integrated products. In addition, Maxim Integrated's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim Integrated's quality and reliability standards.

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I. Device Description

A. General

The MAX14690 is a battery-charge-management solution ideal for low-power wearable applications. The device includes a linear battery charger with a smart power selector and several power-optimized peripherals. The MAX14690 features two ultra-low-power buck regulators with a typical quiescent current of 900nA. In addition, three ultra-low power low-dropout (LDO) linear regulators, with a typical quiescent current of 600nA are included. In total, the MAX14690 can provide up to five regulated voltages, each with an ultra-low quiescent current, critical to battery life for the unique power profile in 24/7 operation devices, such as those in the wearable market. The battery charger features a smart power selector that allows operation on a dead battery when connected to a power source. To avoid overloading a power adapter, the input current to the smart power selector is limited based on an I^2C register setting. If the charger power source is unable to supply the entire system load, the smart power control circuit supplements the system load with current from the battery. The two synchronous, high-efficiency step-down buck regulators feature a fixed-frequency PWM mode for tighter regulation and a burst mode for increased efficiency during light-load operation. The output voltage of these regulators can be programmed through I^2C with the default preconfigured. The three configurable LDOs each have a dedicated input pin. Each LDO regulator output voltage can be programmed through I^2C with the default preconfigured. The linear regulators can also be configured to operate as power switches that may be used to disconnect the quiescent load of the system peripherals. The MAX14690 features a programmable power controller that allows the device to be configured for applications that require the device be in a true-off, or always-on, state. The controller also provides a delayed reset signal and voltage sequencing.
The MAX14690 is available in a 36-bump, 0.4mm pitch, 2.72mm x 2.47mm wafer-level package (WLP).

II. Manufacturing Information

A. Description/Function:	Wearable Charge Management Solution
B. Process:	S18
C. Number of Device Transistors:	119252
D. Fabrication Location:	USA
E. Assembly Location:	USA, Taiwan
F. Date of Initial Production:	December 19, 2014

III. Packaging Information

A. Package Type:	36-bmp WLP
B. Lead Frame:	N/A
C. Lead Finish:	N/A
D. Die Attach:	None
E. Bondwire:	N/A (N/A mil dia.)
F. Mold Material:	None
G. Assembly Diagram:	#05-9000-5711
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	N/A°C/W
K. Single Layer Theta Jc:	N/A°C/W
L. Multi Layer Theta Ja:	46°C/W
M. Multi Layer Theta Jc:	N/A°C/W

IV. Die Information

A. Dimensions:	107.0866 X 97.2441 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	0.23 microns (as drawn)
F. Minimum Metal Spacing:	0.23 microns (as drawn)
G. Bondpad Dimensions:	
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Don Lipps (Manager, Reliability Engineering) Bryan Preeshl (Vice President of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% for all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{192 \times 4340 \times 80 \times 2}$$ (Chi square value for MTTF upper limit)

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 13.7 \times 10^{-9}$

$\lambda = 13.7$ F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim Integrated's reliability monitor program. Maxim Integrated performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at http://www.maximintegrated.com/qa/reliability/monitor. Cumulative monitor data for the S18 Process results in a FIT Rate of 0.05 @ 25°C and 0.93 @ 55°C (0.8 eV, 60% UCL)

B. E.S.D. and Latch-Up Testing

The AL79-0 die type has been found to have all pins able to withstand an HBM transient pulse of +/-2000V per JEDEC JESD22-A114. Latch-Up testing has shown that this device withstands a current of +/-250mA and overcurrent per JEDEC JESD78.

Table 1

Reliability Evaluation Test Results

MAX14690_EWX+T

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENT
Static Life Test (Note 1)					
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	80	0	

Note 1: Life Test Data may represent plastic DIP qualification lots.